Build in Biasing Circuit MOS FET IC VHF RF Amplifier

HITACHI

ADE-208-573 A (Z) 2nd. Edition September 1997

Features

- Build in Biasing Circuit; To reduce using parts cost & PC board space.
- Low noise characteristics; (NF = 1.7 dB typ. at f = 200 MHz)
- Withstanding to ESD;
 Build in ESD absorbing diode. Withstand up to 240V at C=200pF, Rs=0 conditions.
- Provide mini mold packages; CMPAK-4(SOT-343mod)

Outline

CMPAK-4 3 1. Source 2. Gate1 3. Gate2 4. Drain

- Note 1 Marking is "BW-".
- Note 2 BB302C is individual type number of HITACHI BBFET.



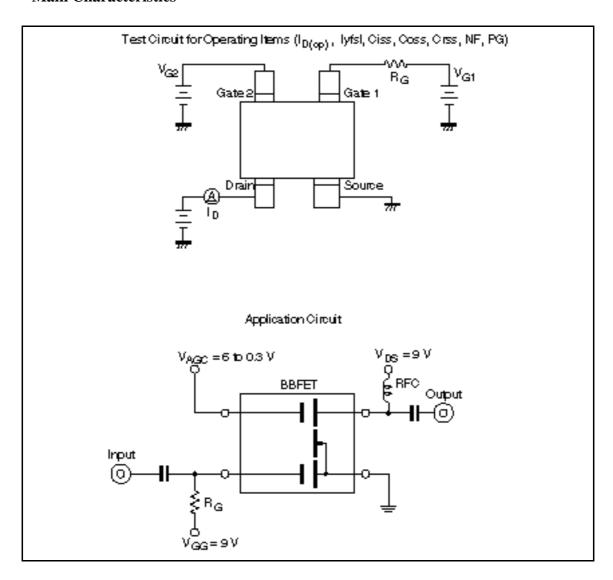
Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

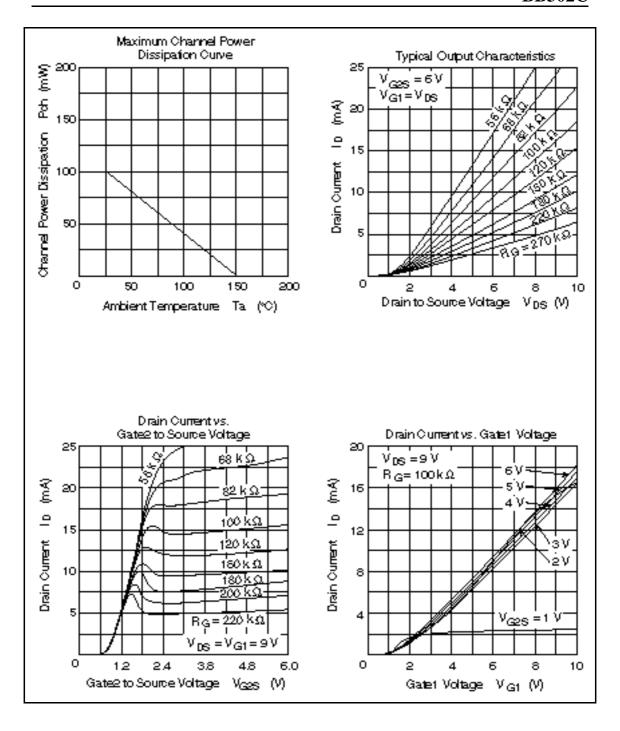
Item	Symbol	Ratings	Unit	
Drain to source voltage	V_{DS}	12	V	
Gate1 to source voltage	V_{G1S}	+10	V	
		-0		
Gate2 to source voltage	V_{G2S}	±10	V	
Drain current	I _D	25	mA	
Channel power dissipation	Pch	100	mW	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

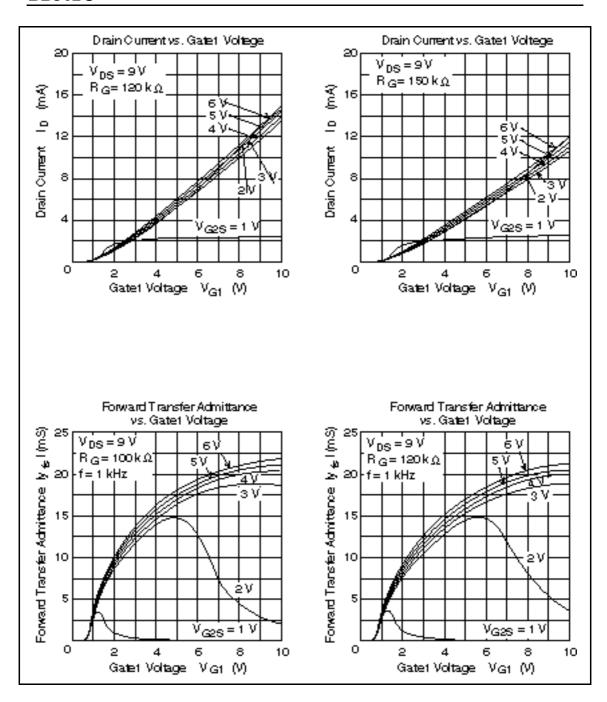
Electrical Characteristics ($Ta = 25^{\circ}C$)

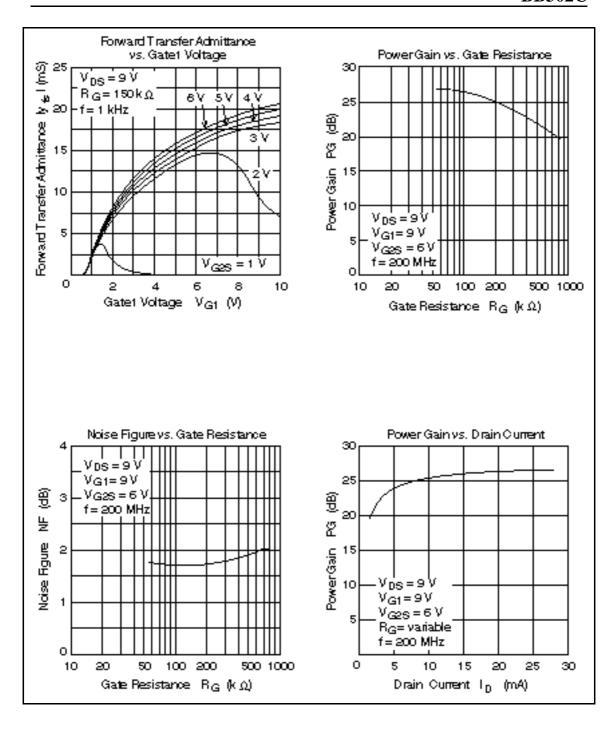
Item	Symbol	Min	Тур	Max	Unit	Test Conditions	
Drain to source breakdown	$V_{(BR)DSS}$	12	_	_	V	I _D = 200μA	
voltage						$V_{\text{G1S}} = V_{\text{G2S}} = 0$	
Gate1 to source breakdown	$V_{(BR)G1SS}$	+10	_	_	V	I _{G1} = +10μA	
voltage						$V_{G2S} = V_{DS} = 0$	
Gate2 to source breakdown	$V_{(BR)G2SS}$	±10	_	_	V	$I_{G2} = \pm 10 \mu A$	
voltage						$V_{G1S} = V_{DS} = 0$	
Gate1 to source cutoff current	I _{G1SS}	_	_	+100	nA	V _{G1S} = +9V	
						$V_{G2S} = V_{DS} = 0$	
Gate2 to source cutoff current	I _{G2SS}	_	_	±100	nA	$V_{G2S} = \pm 9V$	
						$V_{G1S} = V_{DS} = 0$	
Gate1 to source cutoff voltage	$V_{\text{G1S(off)}}$	0.4	_	1.0	V	$V_{DS} = 9V, V_{G2S} = 6V$	
						$I_{D} = 100 \mu A$	
Gate2 to source cutoff voltage	$V_{\text{G2S(off)}}$	0.4	_	1.0	V	$V_{DS} = 9V$, $V_{G1S} = 9V$	
						$I_{D} = 100 \mu A$	
Drain current	I _{D(op)}	9	13	18	mA	$V_{DS} = 9V, V_{G1} = 9V$	
						$V_{G2S} = 6V$	
						R _G = 120k	
Forward transfer admittance	y _{fs}	15	20	_	mS	$V_{DS} = 9V, V_{G1} = 9V$	
						$V_{G2S} = 6V$	
						$R_G = 120k$, $f = 1kHz$	
Input capacitance	C _{iss}	2.2	3.0	4.0	pF	$V_{DS} = 9V, V_{G1} = 9V$	
Output capacitance	C _{oss}	0.8	1.1	1.5	pF	$V_{G2S} = 6V, R_G = 120k$	
Reverse transfer capacitance	C _{rss}	_	0.017	0.04	pF	f = 1MHz	
Power gain	PG	22	26	_	dB	$V_{DS} = 9V, V_{G1} = 9V$	
						V _{G2S} =6V	
Noise figure	NF	_	1.7	2.2	dB	R _G = 120k	
						f = 200MHz	

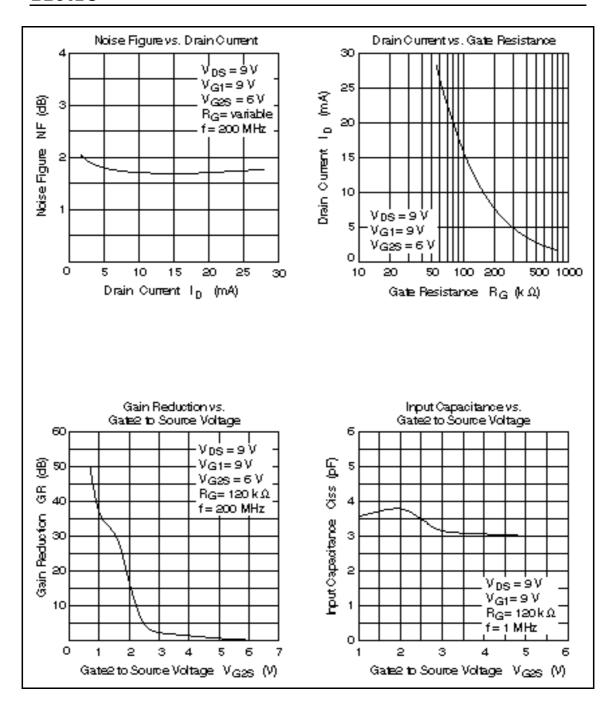
Main Characteristics

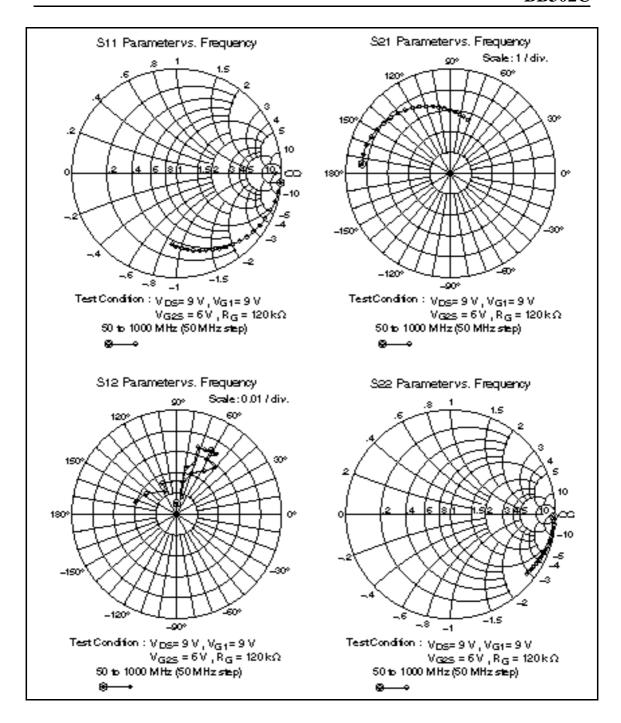










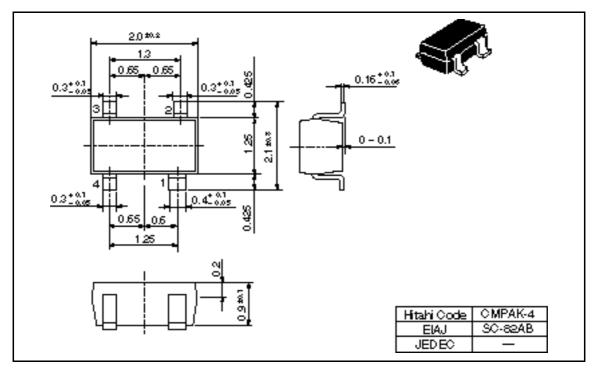


 $\textbf{Sparameter} \; (V_{DS} = V_{G1} = 9V, \; V_{G2S} = 6V, \; R_G = 120k \quad , \; Zo = 50 \quad)$

	S11		S21		S12		S22	
f (MHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
50	0.988	-5.2	2.13	174.1	0.00052	90.0	0.985	-1.3
100	0.986	-10.4	2.13	167.9	0.00087	72.5	0.993	-3.6
150	0.979	-16.0	2.12	161.6	0.00156	79.4	0.992	-5.5
200	0.964	-21.5	2.08	155.2	0.00226	78.4	0.990	-7.5
250	0.948	-26.9	2.04	149.1	0.00254	71.0	0.987	-9.6
300	0.939	-32.0	2.00	143.0	0.00339	72.0	0.985	-11.4
350	0.920	-37.3	1.95	137.3	0.00335	59.0	0.982	-13.3
400	0.904	-42.3	1.91	131.5	0.00338	66.3	0.978	-15.3
450	0.885	-47.1	1.86	125.7	0.00351	62.2	0.974	-17.1
500	0.864	-51.7	1.81	120.1	0.00347	56.6	0.970	-18.9
550	0.848	-56.5	1.76	115.1	0.00355	61.5	0.966	-21.0
600	0.826	-60.9	1.70	110.1	0.00300	61.4	0.961	-22.7
650	0.808	-65.0	1.66	104.7	0.00289	51.1	0.957	-24.5
700	0.789	-69.4	1.61	100.3	0.00246	57.6	0.952	-26.6
750	0.773	-73.7	1.56	95.4	0.00211	70.0	0.947	-28.3
800	0.755	-77.9	1.51	90.5	0.00166	77.5	0.943	-30.2
850	0.735	-82.1	1.47	85.9	0.00165	114.5	0.937	-32.2
900	0.721	-86.3	1.42	81.3	0.00123	114.5	0.933	-34.1
950	0.703	-90.7	1.39	76.9	0.00176	145.8	0.927	-35.9
1000	0.677	-93.9	1.34	72.4	0.00204	164.0	0.923	-37.9

Package Dimensions

Unit: mm



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